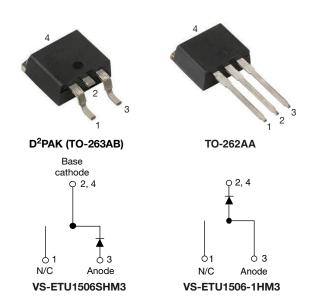
VS-ETU1506SHM3, VS-ETU1506-1HM3

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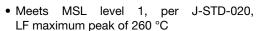
Ultrafast Rectifier, 15 A FRED Pt®



PRIMARY CHARACTERISTICS							
Package	D ² PAK (TO-263AB), TO-262AA						
I _{F(AV)}	15 A						
V_{R}	600 V						
V _F at I _F	1.1 V						
t _{rr} (typ.)	24 ns						
T _J max.	175 °C						
Circuit configuration	Single						

FEATURES

- Low forward voltage drop
- · Ultrafast recovery time
- 175 °C operating junction temperature
- · Low leakage current
- AEC-Q101 qualified, meets JESD 201 class 1 whisker test



 Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





COMPLIANT HALOGEN FREE

DESCRIPTION

State of the art, ultralow V_F , soft-switching ultrafast rectifiers optimized for Discontinuous (Critical) Mode (DCM) Power Factor Correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adapters, desktop PC, TV and monitor, games units, and DVD AC/DC power supplies.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS					
Repetitive peak reverse voltage	V_{RRM}		600	V					
Average rectified forward current	I _{F(AV)}	T _C = 143 °C	15	٨					
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	160	A					
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C					

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-				
Forward voltage	V _F	I _F = 15 A	-	1.35	1.9	V			
		I _F = 15 A, T _J = 150 °C	-	1.1	1.3				
B		$V_R = V_R$ rated	-	0.01	15				
Reverse leakage current	I _R	T _J = 150 °C, V _R = V _R rated	-	- 20 200		μΑ			
Junction capacitance	C _T	V _R = 600 V	-	12	-	pF			
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nΗ			

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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS			
		$I_F = 1 A, dI_F/dt = 1$	$I_F = 1 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$			28			
Reverse recovery time	t _{rr}	T _J = 25 °C		-	40	-	ns		
		T _J = 125 °C	$I_F = 15 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 390 \text{ V}$	-	87	-			
Deels we consent a summent	I _{RRM}	T _J = 25 °C		-	5	-	- A		
Peak recovery current		T _J = 125 °C		-	9.0	-			
Poverse receivent charge	Q _{rr}	T _J = 25 °C		-	107	-			
Reverse recovery charge		T _J = 125 °C		-	430	-			
Reverse recovery time	t _{rr}		I _E = 15 A	-	53	-	ns		
Peak recovery current	I _{RRM}	T _J = 125 °C	$dI_F/dt = 800 A/\mu s$	-	25	-	Α		
Reverse recovery charge	Q _{rr}		V _R = 390 V	-	730	-	nC		

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C			
Thermal resistance, junction to case	R _{thJC}		-	-	1.51	°C/W			
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	70				
Thermal resistance, case to heat sink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-				
Woight			-	2.0	-	g			
Weight			-	0.07	-	OZ.			
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)			
Marking dayioo		Case style D ² PAK	ETU1506SH			•			
Marking device		Case style TO-262	ETU1506-1H						

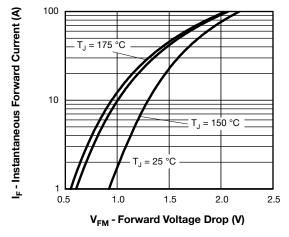


Fig. 1 - Typical Forward Voltage Drop Characteristics

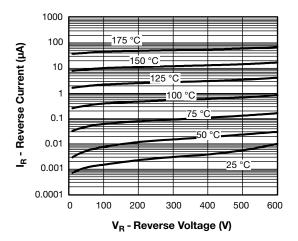


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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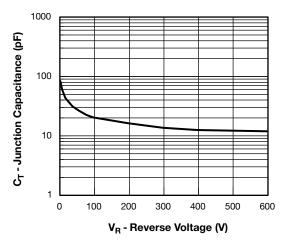


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

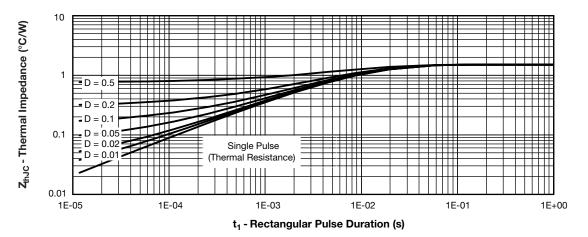


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

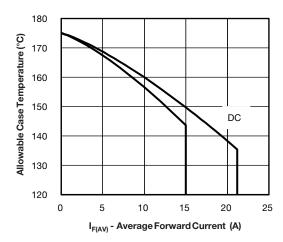


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

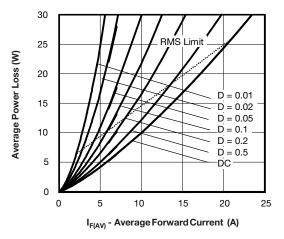


Fig. 6 - Forward Power Loss Characteristics

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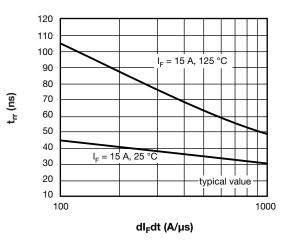


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

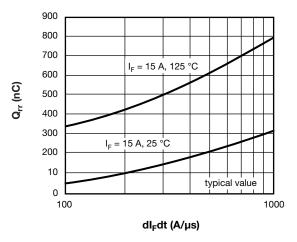
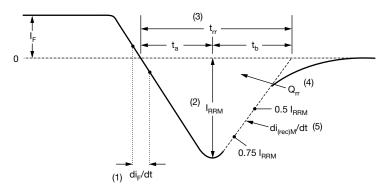


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

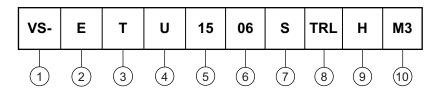
Fig. 9 - Reverse Recovery Waveform and Definitions

VS-ETU1506SHM3, VS-ETU1506-1HM3

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

Circuit configuration
E = single diode

3 - T = TO-220

U = ultrafast recovery time

5 - Current code (15 = 15 A)

- Voltage code (06 = 600 V)

7 - •S = D²PAK

- • -1 = TO-262

8 - • None = tube (50 pieces)

TRL = tape and reel (left oriented, for D²PAK package)

- • TRR = tape and reel (right oriented, for D²PAK package)

9 - H = AEC-Q101 qualified

- M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-ETU1506SHM3	50	Antistatic plastic tube					
VS-ETU1506-1HM3	50	Antistatic plastic tube					
VS-ETU1506STRRHM3	800	13" diameter reel					
VS-ETU1506STRLHM3	800	13" diameter reel					

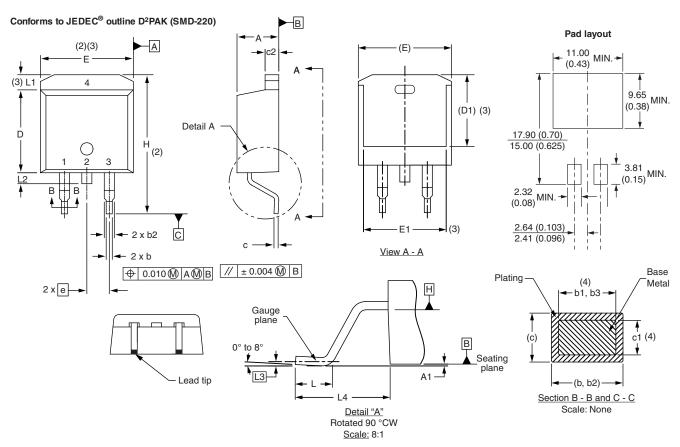
LINKS TO RELATED DOCUMENTS							
Dimensions	TO-263AB (D ² PAK)	www.vishay.com/doc?95046					
Differisions	TO-262AA	www.vishay.com/doc?95419					
Part marking information	TO-263AB (D ² PAK)	www.vishay.com/doc?95444					
	TO-262AA	www.vishay.com/doc?95443					
Packaging information	TO-263AB (D ² PAK)	www.vishay.com/doc?95032					
SPICE model		www.vishay.com/doc?96132					



Vishay Semiconductors

D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	S SYMBOL	MILLIM	ETERS	INC	HES	NOTES	
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOIES	NOTES	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100) BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

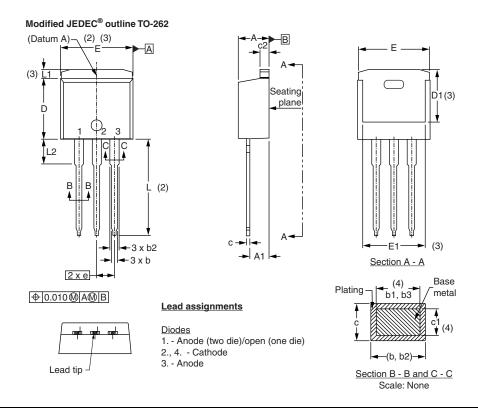
Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB

Vishay Semiconductors

TO-262

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	CHES	NOTES
STIVIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.10	0 BSC	
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- 5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

Revision: 11-Jul-2019 1 Document Number: 95419



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